



AUTOMATED CHEMICAL SOLUTIONS

Chemicals and Controllers for PWB Fabrication

Product Overview

OXYshield AT-2310

Copper Anti-tarnish

Product Description

OXYshield AT-2310 is a concentrated acid solution designed to remove light oxides from copper surfaces and prevent re-oxidation prior to subsequent processing. OXYshield AT-2310 activates the copper surface and deposits a uniform triazole film that promotes excellent dry film adhesion.

Physical Properties

Specific gravity:	1.06
pH:	< 2
Appearance:	clear, water white liquid
Flash point:	> 200 °F

Operating Parameters

Concentration:	1.0 – 2.0% v/v
Temperature:	70 – 100 °F

Storage

Store in original containers above 40 °F.

Safety

CAUTION! AT-2310 concentrates and working solutions contain strong acidic ingredients. Avoid contact with eyes, skin and clothing. Wear chemical handler's gloves, goggles and protective clothing when handling. Read and understand Material Safety Data Sheet before using this product.

Notice

The information and recommendations of Automated Chemical Solutions, Inc., and its representatives, regarding this product are, to the best of our knowledge, true and accurate. We make no guarantee of results because the conditions of actual use are beyond our control. We assume no liability for damages or penalties resulting from the use of this product or following our recommendations. Our recommendations and suggestions for use of this product are not intended to grant license to operate under or infringe any patent.